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(54) **ELECTRONIC PART, ELECTRODE SURFACE TREATMENT THEREOF AND ITS DEVICE**

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(57) Abstract

PROBLEM TO BE SOLVED: To improve bonding property between a cut surface of a lead and solder by performing surface treatment for a cut surface of a lead of an IC package.

SOLUTION: A light irradiation means for casting light on a cut surface 2a of a lead 2 of an IC package 1 of a QFP(quad flat package) type IC. The light irradiation means can be constituted by using, for example, a YAG laser device 3 of Q switch control and four optical fibers 4 as an optical system which introduce laser beam from the YAG laser device 3 to the cut surface 2a of a tip of each lead 2 which is an object of irradiation. After the lead 2 of the IC package 1 is cut, antioxidant such as flux can be applied to the cut surface.

